

Part Number: WP819IID

High Efficiency Red

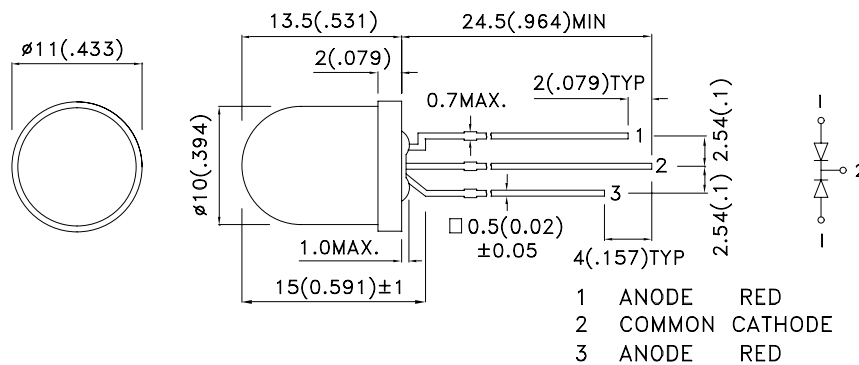
Features

- UNIFORM LIGHT OUTPUT.
- LOW POWER CONSUMPTION.
- 3 LEADS WITH ONE COMMON CATHODE LEAD.
- I.C. COMPATIBLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP819IID	High Efficiency Red (GaAsP/GaP)	RED DIFFUSED	36	80	50°
	High Efficiency Red (GaAsP/GaP)		36	80	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	High Efficiency Red	627		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	High Efficiency Red	625		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	High Efficiency Red	45		nm	I _F =20mA
C	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	High Efficiency Red	2	2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red		10	uA	V _R = 5V

Notes:

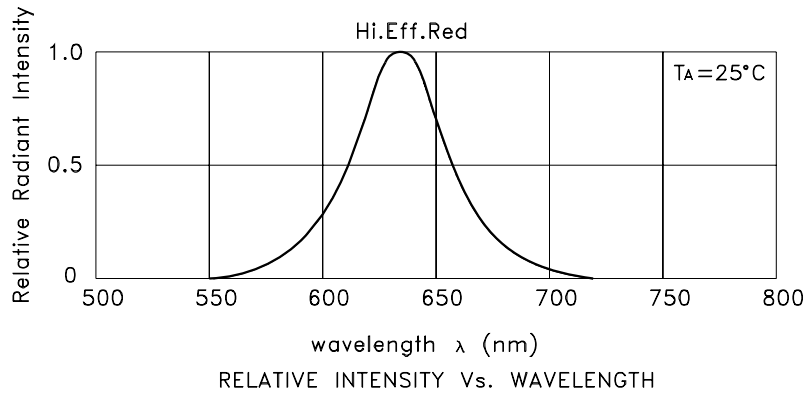
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

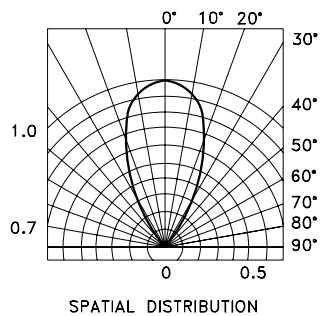
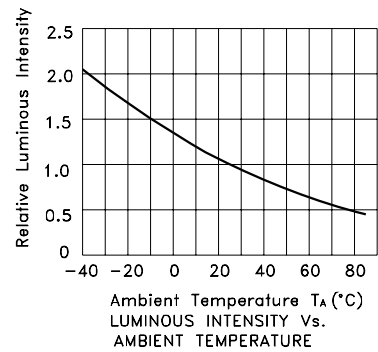
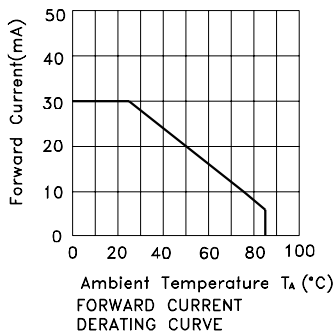
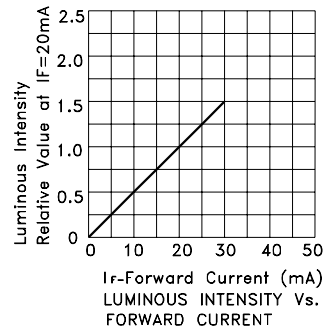
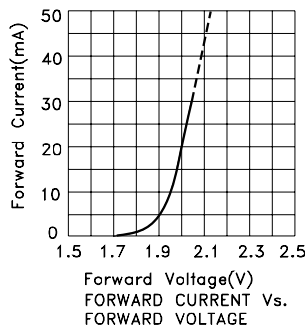
Parameter	High Efficiency Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



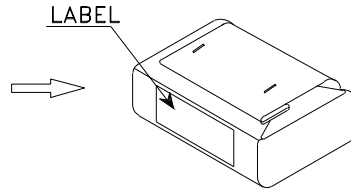
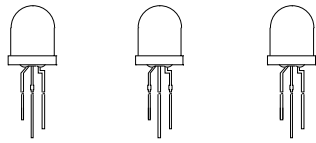
High Efficiency Red WP819IID



Kingbright

PACKING & LABEL SPECIFICATIONS

WP819IID

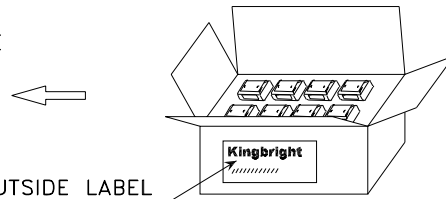


200PCS / BAG




8K / 9# BOX

OUTSIDE LABEL



OUTSIDE LABEL

1K / 1# BOX

Kingbright				
Q.C.	<table border="1"> <tr> <td style="text-align: center;">QC</td> </tr> <tr> <td style="text-align: center;">XX XX XXXX</td> </tr> <tr> <td style="text-align: center;">PASSED</td> </tr> </table>	QC	XX XX XXXX	PASSED
QC				
XX XX XXXX				
PASSED				
TYPE NO :	WP819XXX			
QUANTITY :	200 pcs			
S/N :	XXX			
	CODE: XXX			
LOT NO:				
	RoHS Compliant			

LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)



Fig.1

“○” Correct mounting method “X” Incorrect mounting method

Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.

(Fig. 2)



Fig. 2

3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

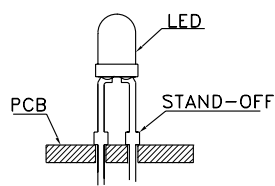


Fig. 3



Fig. 4

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



Fig. 5



Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)

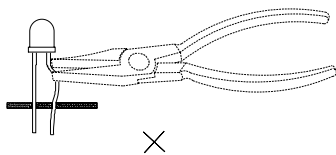


Fig. 7

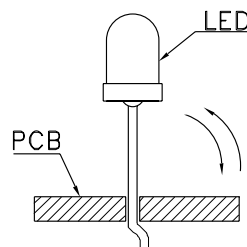


Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



Fig. 9

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9